# SUPPORTING INFORMATION

# Raman analysis of bilayer graphene film prepared on commercial Cu(0.5 at% Ni) foil

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#### Ni surface concentration calculation using surface segregation models

Part of the modified Darken equations, which defines the rate of surface concentration build-up of dope element 1 (e.g. Ni in dilute Cu(Ni) foil), is<sup>[1,2]</sup>

$$\frac{\partial X_{1}^{S}}{\partial t} = \frac{M_{1}X_{1}^{B_{1}}}{d^{2}} \left[ \Delta G + RT \ln \frac{X_{1}^{B_{1}} \left(1 - \frac{X_{1}^{S}}{X^{M}}\right)}{\frac{X_{1}^{S}}{X^{M}} (1 - X_{1}^{B_{1}})} \right]$$
(1)

where  $X_1^S$  is the surface concentration of the segregating dope element 1,  $X_1^B$  is the bulk concentration,  $X^M$  is the maximum surface concentration < 100 at%,  $M_1$  is the mobility, M = D/RT where D is the diffusion coefficient in Arrhenius equation, d is the thickness of the segregated layer, R is the gas constant and T is the temperature.

In dilute system the segregation energy ( $\Delta G$ ) can be approximated to segregation enthalpy ( $\Delta H$ ) by <sup>[3,4]</sup>

$$\Delta G \approx \Delta H = \left(\frac{\Delta Z}{Z}\right) \left(\Delta H_B^{sub} - \Delta H_A^{sub}\right) \tag{2}$$

where Z is bulk coordination number (Z = 12 for Cu crystal),  $\Delta Z$  is a difference in coordination number between bulk and surface ( $\Delta Z = 4$ , 3 and 2 for Cu(001), Cu(111) and Cu(101) respectively),  $\Delta H^{\text{sub}}$  is heat of sublimation for element A and B ( $\Delta H_{\text{Cu}}^{\text{sub}} = 339.3 \text{ kJ/mol}$  and  $\Delta H_{\text{Ni}}^{\text{sub}} = 430.1 \text{ kJ/mol}$ )<sup>[5]</sup>.

In Eq. S1, the rate of surface concentration build-up of dope element 1, at equilibrium,  $\partial X_1^s / \partial t = 0$ , and Eq. S1 reduces to the Langmuir–McLean equation<sup>[1,6]</sup>:

$$\frac{X_{1}^{S}/X^{M}}{1-X_{1}^{S}/X^{M}} = \frac{X_{1}^{B}}{1-X_{1}^{B}} \exp\left(\frac{-\Delta G}{RT}\right)$$
(3)

In Eq. S3, substituting parameters:

- i.  $\Delta G$  (obtained from Eq. S2 for Cu(001), Cu(111) and Cu(101)),
- ii.  $X_1^{B_1} = 0.5$  at % and

iii.  $X^{M} = 0.25, 0.33 \text{ and } 0.50 \text{ for Cu}(001), \text{Cu}(111) \text{ and Cu}(101) \text{ respectively}^{[1,6]},$ 

the temperature dependence of the Ni surface fractional concentration in dilute Cu(0.5 at% Ni) foil was obtained as shown in Fig. S1.



**Figure. S1.** The temperature dependence of the Ni surface concentration in dilute Cu(Ni) alloy obtained with Langmuir–McLean equation.

In brief, at isothermal CVD growth temperature of 980 °C the Ni surface concentration in dilute Cu(0.5 at% Ni) foil is  $X_{Ni}^{s} = 2.1$ , 1.4 and 1.1 at% for Cu(001), Cu(111) and Cu(101) surfaces respectively. Therefore, at 980 °C, a surface layer of a dilute Cu(0.5 at% Ni) foil will have about 98.5 at% Cu and 1.5 at% Ni.

### Raman data



**Figure. S2.** The G peaks intensities mapping over 30  $\mu$ m<sup>2</sup> area for monolayer and bilayer graphene films transferred on SiO<sub>2</sub>/Si substrate.



**Figure. S3.** The Raman optical microscope image of bilayer graphene film transferred onto 300 nm thick SiO<sub>2</sub>/Si substrate.



**Figure. S4.** The Raman spectra from two different spots of bilayer graphene film transferred onto  $SiO_2/Si$  substrate. The solid lines are Lorentzian fits of 2D peaks.



**Figure. S5.** The map images of TOF-SIMS secondary ion intensities measured from a dilute Cu(0.5 at% Ni) surface after surface cleaning for 180 s with ion sputtering.

## S1. References

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